

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOS V-H)

# TPC8031-H

High-Efficiency DC/DC Converter Applications  
 Notebook PC Applications  
 Portable Equipment Applications

- Small footprint due to a small and thin package
- High-speed switching
- Small gate charge:  $Q_{sw} = 5.0 \text{ nC}$  (typ.)
- Low drain-source ON-resistance:  $R_{DS(ON)} = 10.1 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 33 \text{ S}$  (typ.)
- Low leakage current:  $I_{DSS} = 10 \text{ }\mu\text{A}$  (max) ( $V_{DS} = 30 \text{ V}$ )
- Enhancement mode:  $V_{th} = 1.5 \text{ to } 2.5 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

## Absolute Maximum Ratings (Ta = 25°C)

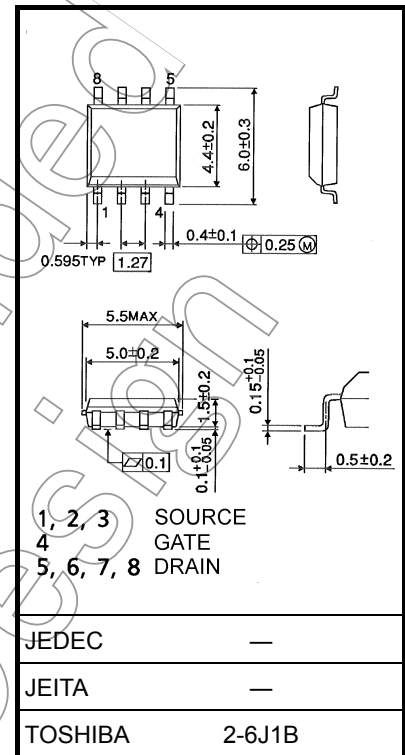
Characteristic		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	30	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	30	V
Gate-source voltage		$V_{GSS}$	$\pm 20$	V
Drain current	DC (Note 1)	$I_D$	11	A
	Pulsed (Note 1)	$I_{DP}$	44	
Drain power dissipation (t = 10 s) (Note 2a)		$P_D$	1.9	W
Drain power dissipation (t = 10 s) (Note 2b)		$P_D$	1.0	W
Single-pulse avalanche energy (Note 3)		$E_{AS}$	79	mJ
Avalanche current		$I_{AR}$	11	A
Repetitive avalanche energy (Note 2a) (Note 4)		$E_{AR}$	0.16	mJ
Channel temperature		$T_{ch}$	150	°C
Storage temperature range		$T_{stg}$	-55 to 150	°C

Note: For Notes 1 to 4, refer to the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

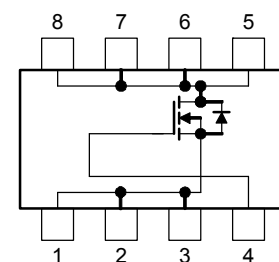
This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 0.085 g (typ.)

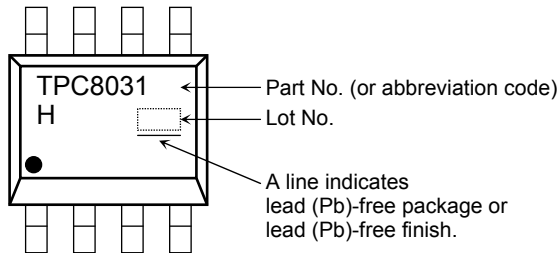
## Circuit Configuration



## Thermal Characteristics

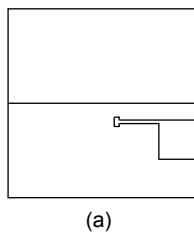
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	$R_{th(ch-a)}$	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	$R_{th(ch-a)}$	125	°C/W

## Marking (Note 5)

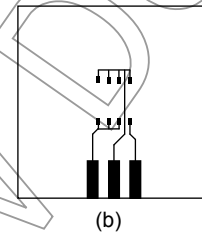


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



FR-4  
 25.4 × 25.4 × 0.8  
 (Unit: mm)



FR-4  
 25.4 × 25.4 × 0.8  
 (Unit: mm)

Note 3:  $V_{DD} = 24\text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 0.5\text{ mH}$ ,  $R_G = 25\ \Omega$ ,  $I_{AR} = 11\text{ A}$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)



Week of manufacture  
 (01 for first week of year, continuing up to 52 or 53)



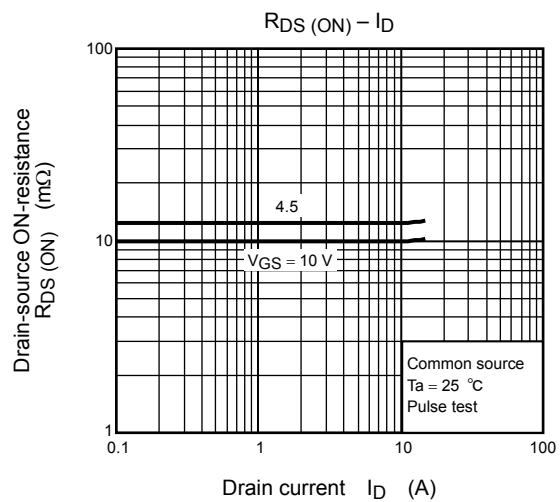
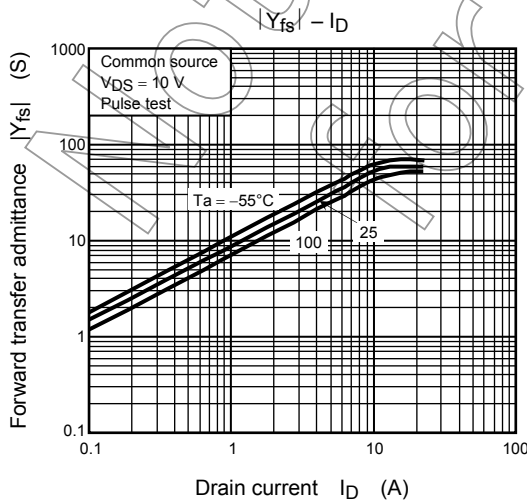
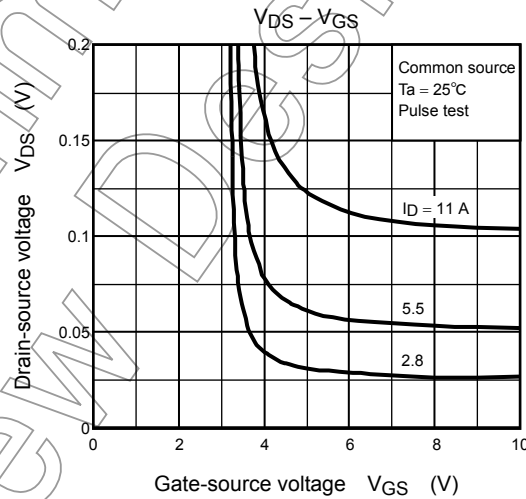
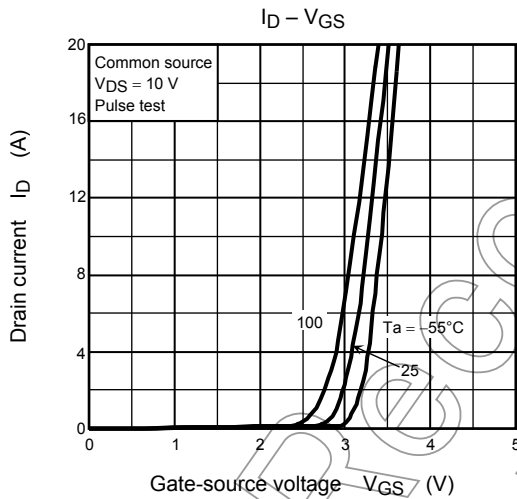
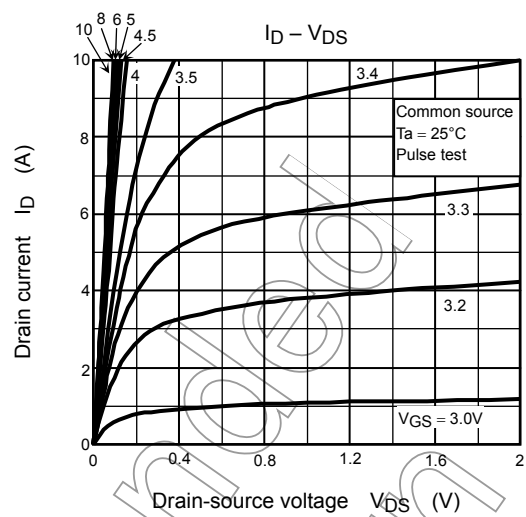
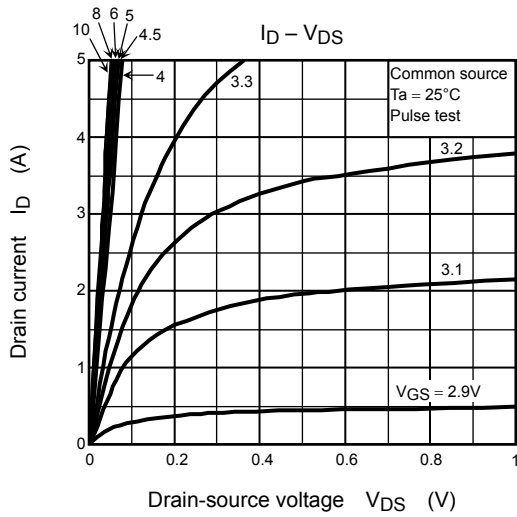
Year of manufacture  
 (The last digit of a year)

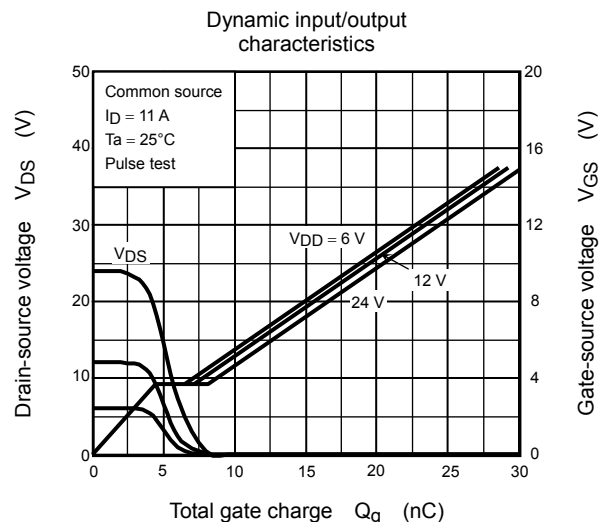
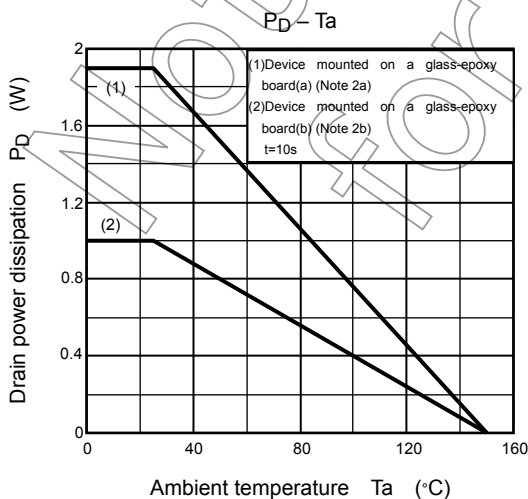
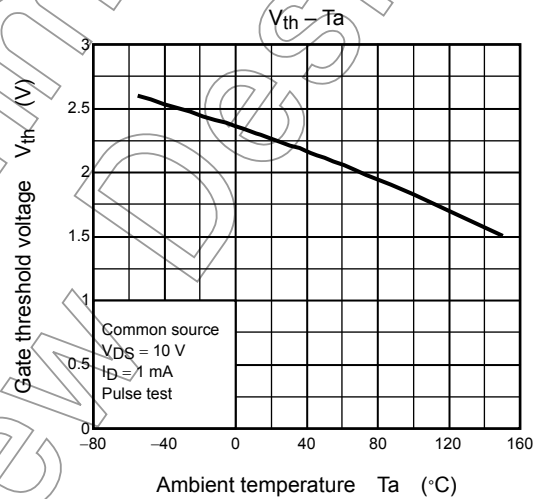
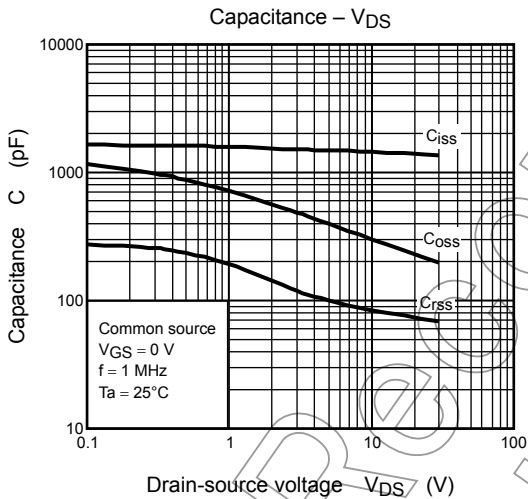
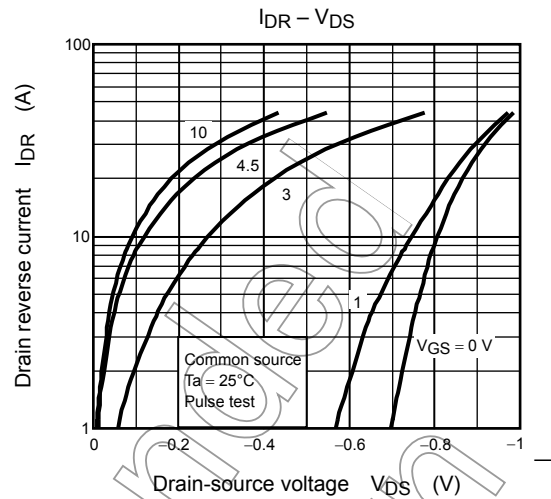
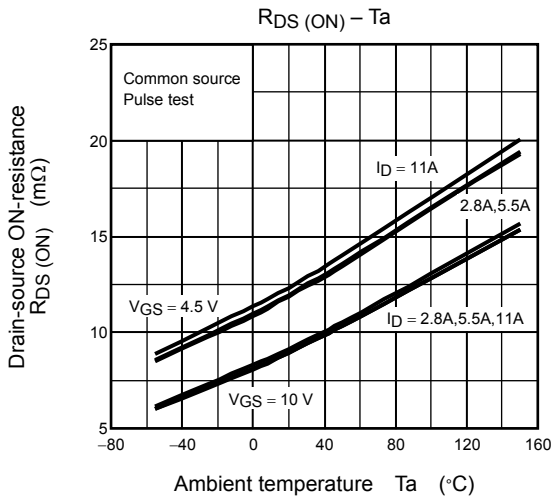
## Electrical Characteristics (Ta = 25°C)

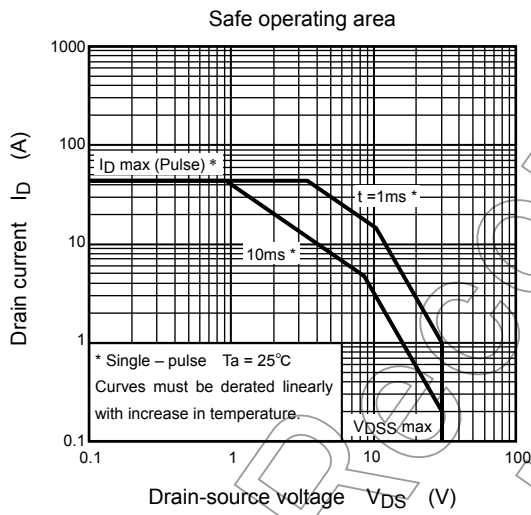
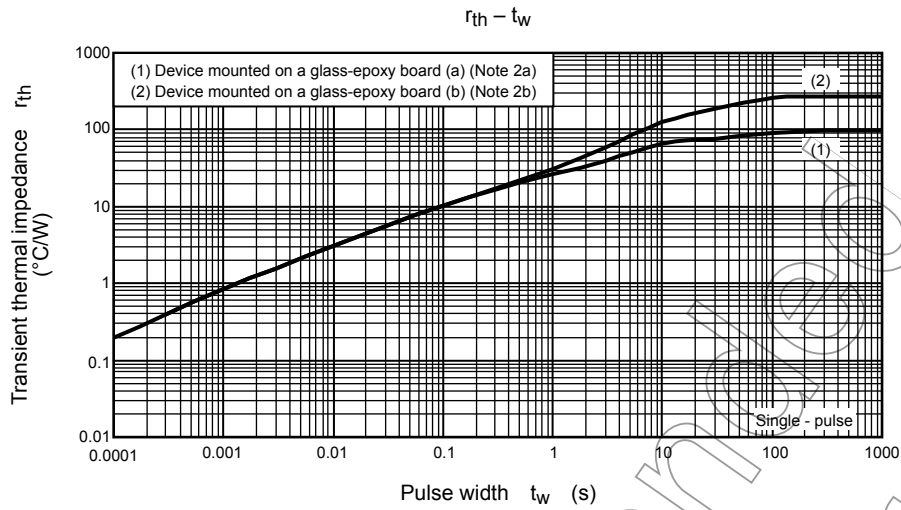
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	—	—	$\pm 100$	nA
Drain cutoff current		$I_{DSS}$	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	$\mu\text{A}$
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	30	—	—	V
		$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$	15	—	—	
Gate threshold voltage		$V_{th}$	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	1.5	—	2.5	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}, I_D = 5.5\text{ A}$	—	12.4	16.1	m $\Omega$
			$V_{GS} = 10\text{ V}, I_D = 5.5\text{ A}$	—	10.1	13.3	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 5.5\text{ A}$	16.5	33	—	S
Input capacitance		$C_{iss}$	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	1433	2150	pF
Reverse transfer capacitance		$C_{rss}$		—	83	125	
Output capacitance		$C_{oss}$		—	303	—	
Gate resistance		$R_g$	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 5\text{ MHz}$	—	1.0	1.5	$\Omega$
Switching time	Rise time	$t_r$		—	3	—	ns
	Turn-on time	$t_{on}$		—	10	—	
	Fall time	$t_f$		—	3.9	—	
	Turn-off time	$t_{off}$		Duty $\leq 1\%$ , $t_w = 10\text{ }\mu\text{s}$	—	23	
Total gate charge (gate-source plus gate-drain)		$Q_g$	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 11\text{ A}$	—	21	—	nC
			$V_{DD} \approx 24\text{ V}, V_{GS} = 5\text{ V}, I_D = 11\text{ A}$	—	11	—	
Gate-source charge 1		$Q_{gs1}$	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 11\text{ A}$	—	4.4	—	
Gate-drain ("Miller") charge		$Q_{gd}$		—	3.7	—	
Gate switch charge		$Q_{sw}$		—	5.0	—	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	$I_{DRP}$	—	—	—	44	A
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = 11\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V







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